### **SPECIFICATIONS**

CUSTOMER .

SAMPLE CODE : SH128800T004-ZFA01

MASS PRODUCTION CODE . PH128800T004-ZFA01

SAMPLE VERSION . 01

SPECIFICATIONS EDITION . 006

DRAWING NO. (Ver.) . LMD-PH128800T004-ZFA01 (Ver.003)

PACKAGING NO. (Ver.) . PKG-PH128800T004-ZFA01 (Ver.003)

# **Customer Approved**

Date:

Approved	Checked	Designer
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Preliminary specification for design input

Specification for sample approval

2018.12.21 TW RD APR

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# **History of Version**

Date	Ver.	Edi.	Description	Page	Design by
04/11/2017	01	001	New Drawing.	-	Stephen
05/20/2017	01	002	New Sample	-	Stephen
07/19/2017	01	003	Modify Spec Update Packages Version	10	Stephen
10/18/2017	01	004	Modify Specifications Features	4	Stephen
10/10/2017	01	004	Update LCD Module Drawing Version	-	Stephen
05/09/2018	01	005	Modify Spec	-//	Stephen
12/20/2018	01	006	Modify Spec 1.1 Features - Display Mode 1.3 Maximum Ratings - Operating Temperature 1.4 DC Electrical Characteristics	4 \ 5	Stephen
		X			

Total: 27 Page



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**Appendix: LCM Drawing.** 

**LCM Packaging Specifications** 



### 1. SPECIFICATIONS

### 1.1 Features

Item	Standard Value
Screen Size(inch)	10.1(Diagonal)
Resolution	1280* (R · G · B) * 800 Dots
Display Mode	Full Viewing Angle . Transmissive . Normally Black
Color	16.7M
Weight	256.7 g
Interface	HDMI
	THIS PRODUCT CONFORMS THE ROHS OF PTC
ROHS	Detail information please refer website:
	http://www.powertip.com.tw/news_detail.php?Key=1&cID=1

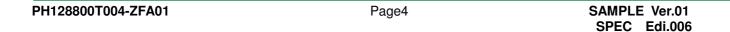
# 1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	229.8(W) * 149.0 (L) * 23.6 (H)	mm

# LCD panel

Item	Standard Value	Unit
Active Area	216.96 (W) * 135.60 (L)	mm

Note: For detailed information please refer to LCM drawing.





# 1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	VCC	-	-0.3	+23.0	V
Tower Supply Voltage	VBus	-	-0.3	+6.0	V
Logic Voltage	BL_PWM	-	-0.3	+5.5	V
Operating Temperature	T <sub>OP</sub>	-	-20	+70	$^{\circ}$ C
Storage Temperature	T <sub>ST</sub>	-	-30	+80	$^{\circ}\!\mathbb{C}$
Storage Humidity	H <sub>D</sub>	Ta<60 °C	-	90	%RH

# 1.4 DC Electrical Characteristics

Item	Symbol	Status	Condition	Min.	Тур.	Max.	Unit
Power Supply	VCC	I	VCC-GND	11.5	12.0	12.5	V
Voltage	VBus	_	V <sub>Bus</sub> -GND	4.75	5.0	5.25	V
Power Supply	ICC	(	VCC=12.0v	-	500	550	mA
Current	lBus	_	V <sub>Bus</sub> =5.0v	-	50	100	mA
Logic Voltage	BL_PWM	·	BL_EN=5.0v	0	ı	5.0	V
PWM Frequency	FPWM	-		100	-	20000	HZ

Note: Maximum current from RGB full-display





### 1.5 Optical Characteristics

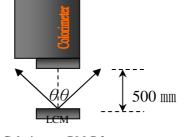
TFT LCD Panel Ta=25 ℃

Item		Symbol	Condition	Min.	Тур.	Max.	Unit	-
Response Tin	ne	Tr + Tf	-	-	25	50	ms	Note2
	Тор	ΘΥ+		75	85	-		
Viouing Anglo	Bottom	ΘΥ-	CR ≥ 10	75	85	1	Dog	Note4
Viewing Angle	Left	ΘХ-	ON 2 10	75	85	1	Deg.	Note4
	Right	ΘХ+		75	85	1		
Contrast Rat	io	CR		600	800	ı	1	Note3
	White	Χ		0.268	0.318	0.368		
	vviile	Υ		0.302	0.352	0.402		
0 1 (0)5	Dad	Х		0.541	0.591	0.641		
Color of CIE	Red	Υ	-	0.300	0.350	0.400		Nicia
Coordinate (With B/L)	Green	X		0.293	0.343	0.393	-	Note1
(**************************************	arcon	Υ		0.534	0.584	0.634		
	Blue	Χ		0.104	0.154	0.204		
	blue	Υ		0.099	0.149	0.199		
Average Brightr Pattern=White D		IV	IF=80 mA	400	500	-	cd/m2	Note1
Luminance Unifo	ormity	YU	IF=80 mA	70	75	-	%	Note1

#### Note1:

- $1 : \triangle B=B(min) / B(max) \times 100\%$
- 2 : Measurement Condition for Optical Characteristics:
  - a: Environment: 25°C±5°C / 60±20%R.H → no wind → dark room below 10 Lux at typical lamp current and typical operating frequency.
  - b : Measurement Distance: 500  $\pm$  50 mm  $\cdot$  ( $\theta$ = 0°)
  - c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
  - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%





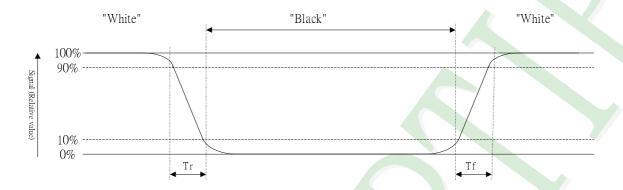
Colorimeter=BM-7 fast



#### Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:



Note3: Definition of contrast ratio:

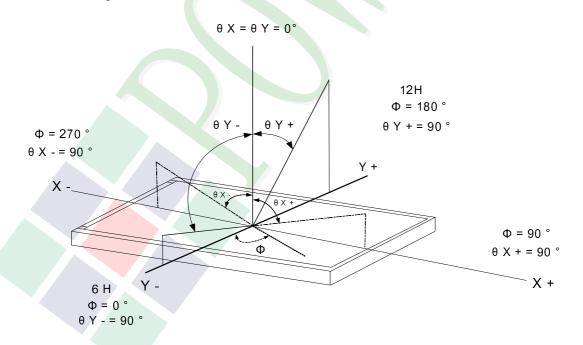
Contrast ratio is calculated with the following formula

Photo detector output when LCD is at "White" state

Contrast ratio (CR) =

Photo detector output when LCD is at "Black" state

# Note4: Definition of viewing angle: Refer to figure as below:





### 1.6 Backlight Characteristics

Maximum Ratings

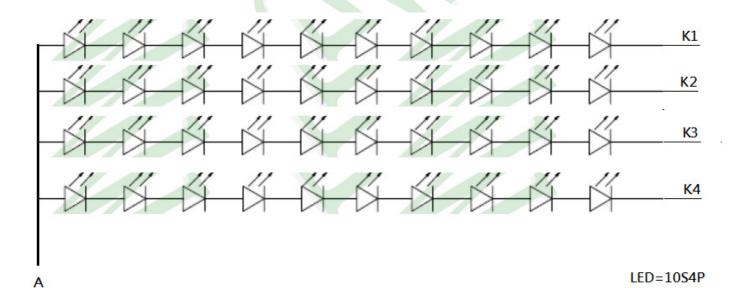
Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Power Dissipation	Pd	-	-	100	-	mW
LED Forward Current	IF	1 LED	-	-	30	mA
LED Reverse Voltage	VR	1 LED	-	-	1.2	V

### Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Voltage for LED Backlight	VF	If=80mA	27.5	31.0	34.0	V
Current for LED Backlight	IF	II=OUIIIA	-	80	<b>\</b>	mA
Color	White					

Other Description

Item	Conditions	Description
Life Time	Ta =25°C If= 80 mA	50000 hrs



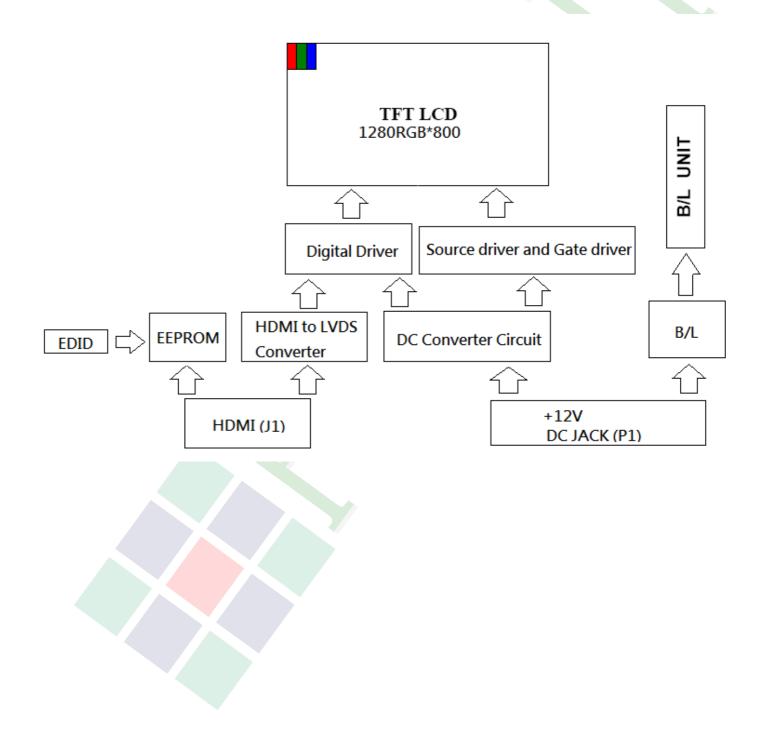
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### 2. MODULE STRUCTURE

# 2.1 Counter Drawing

- 2.1.1 LCM Mechanical Diagram
  - \* See Appendix
- 2.1.2 Block Diagram





# 2.2 Interface Pin Description

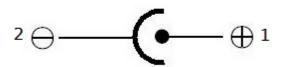
# 2.2.1 (J1:HDMI 1.3 A type Interface)

Pin#	Name	Description
1	TX2+	TMDS Data 2+
2	TX2 Shield	TMDS Data 2 Shield
3	TX2-	TMDS Data 2-
4	TX1+	TMDS Data 1+
5	TX1 Shield	TMDS Data 1 Shield
6	TX1-	TMDS Data 1-
7	TX0+	TMDS Data 0+
8	TX0 Shield	TMDS Data 0 Shield
9	TX0-	TMDS Data 0-
10	TXC+	TMDS Clock+
11	TXC Shield	TMDS Clock Shield
12	TXC-	TMDS Clock-
13	CEC	CEC
14	NC	No connection
15	SCL	Serial Clock for DDC
16	SDA	Serial Data for DDC
17	GND	Power Ground
18	V5V	No connection
19	Hot Plug Detect	Hot Plug Detect



# 2.2.2 (PJ1:POWER DC JACK Interface)

PJ1



Hold Φ6.4mm / Center Pin Φ 2.0mm

Pin#	Name	Description
1	VCC	+12V Power
2	GND	Power Ground



### 2.3 HDMI Characteristics

### 2.3.1 Signal DC&AC Characteristics

#### DC ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP MAX	UNIT
$V_{\text{ID}}$	Analog input differential voltage (1)		75	1200	mV
$V_{IC}$	Analog input common-mode voltage <sup>(1)</sup>		AV <sub>DD</sub> – 300	$AV_{DD} - 37$	mV
V <sub>I(OC)</sub>	Open-circuit analog input voltage		AV <sub>DD</sub> – 10	AV <sub>DD</sub> + 10	mV
I <sub>DD(2PIX)</sub>	Normal 2-pix/clock power supply current (2)	ODCK = 82.5 MHz, 2-pix/clock		370	mA
I <sub>PD</sub>	Power-down current (3)	PD = low		10	mA
I <sub>PDO</sub>	Output drive power-down current <sup>(3)</sup>	PDO = low		35	mA

(1) Specified as dc characteristic with no overshoot or undershoot

(2) Alternating 2-pixel black/2-pixel white pattern. ST = high,  $\overline{\text{STAG}}$  = high, QE[23:0] and QO[23:0]  $C_L$  = 10 pF.

(3) Analog inputs are open circuit (transmitter is disconnected from TFP401/401A).

#### AC ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>ID(2)</sub>	Differential input sensitivity <sup>(1)</sup>		150		1560	mV <sub>p-p</sub>
t <sub>ps</sub>	Analog input intra-pair (+ to –) differential skew (2)				0.4	t <sub>bit</sub> (3)
t <sub>ccs</sub>	Analog input inter-pair or channel-to-channel skew (2)				1	t <sub>pix</sub> (4)
t <sub>ijit</sub>	Worst-case differential input clock jitter tolerance (2)(5)		50			ps
+	Fall time of data and control signals (6)(7)	ST = low, C <sub>L</sub> = 5 pF			2.4	ns
t <sub>f1</sub>	Fall time of data and control signals	ST = high, C <sub>L</sub> = 10 pF			1.9	115
+	Rise time of data and control signals <sup>(6)(7)</sup>	ST = low, C <sub>L</sub> = 5 pF			2.4	ne
ţ <sub>1</sub>	Rise time of data and control signals (A)	ST = high, C <sub>L</sub> = 10 pF			1.9	ns
	Rise time of ODCK clock (6)	ST = low, C <sub>L</sub> = 5 pF			2.4	
t <sub>r2</sub>	Rise time of ODCR dock**	ST = high, C <sub>L</sub> = 10 pF			1.9	ns
	Fall time of ODCK clock <sup>(6)</sup>	ST = low, C <sub>L</sub> = 5 pF			2.4	
t <sub>f2</sub>	Fall time of ODCK clock*	ST = high, C <sub>L</sub> = 10 pF			1.9	ns
		1 pixel/clock, PIXS = low, OCK_INV = low	1.8			
t <sub>su1</sub>	Setup time, data and control signal to falling edge of ODCK	2 pixel/clock, PIXS = high, STAG = high, OCK_INV = low	3.8			ns
		2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = low	0.7			
		1 pixel/clock, PIXS = low, OCK_INV = low	0.6			
t <sub>h1</sub>	Hold time, data and control signal to falling edge of ODCK	2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = low	2.5			ns
		2 pixel/clock, PIXS = high, STAG = high, OCK_INV = low	2.9			

Specified as ac parameter to include sensitivity to overshoot, undershoot and reflection.

(2) By characterization

(3) t<sub>bit</sub> is 1/10 the pixel time, t<sub>pix</sub>

(5) Measured differentially at 50% crossing using ODCK output clock as trigger

(6) Rise and fall times measured as time between 20% and 80% of signal amplitude.

<sup>4)</sup> t<sub>pix</sub> is the pixel time defined as the period of the RxC input clock. The period of ODCK is equal to t<sub>pix</sub> in 1-pixel/clock mode or 2t<sub>pix</sub> when in 2-pixel/clock mode.

<sup>(7)</sup> Data and control signals are QE[23:0], QO[23:0], DE, HSYNC, VSYNC. and CTL[3:1].



### AC ELECTRICAL CHARACTERISTICS (continued)

over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
		1 pixel/clock, PIXS = low, OCK_INV = high	2.1			
t <sub>su2</sub>	Setup time, data and control signal to rising edge of ODCK	2 pixel/clock, PIXS = high, STAG = high, OCK_INV = high	4			ns
		2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = high	1.5			
		1 pixel/clock, PIXS = low, OCK_INV = high	0.5			
t <sub>h2</sub>	Hold time, data and control signal to rising edge of ODCK	2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = high	2.4			ns
		2 pixel/clock, PIXS = high, STAG = high, OCK_INV = high	2.1			
	ODCK fraguancy	PIX = low (1-PIX/CLK)	25		165	MHz
f <sub>ODCK</sub>	ODCK frequency	PIX = high (2-PIX/CLK)	12.5		82.5	IVIHZ
	ODCK duty-cycle		40%	50%	60%	
t <sub>pd(PDL)</sub>	Propagation delay time from PD low to Hi-Z outputs				9	ns
t <sub>pd(PDOL)</sub>	Propagation delay time from PDO low to Hi-Z outputs				9	ns
t <sub>t(HSC)</sub>	Transition time between DE transition to SCDT low <sup>(8)</sup>			1e6		t <sub>pix</sub>
t <sub>t(FSC)</sub>	Transition time between DE transition to SCDT high <sup>(8)</sup>			1600		t <sub>pix</sub>
t <sub>d(st)</sub>	Delay time, ODCK latching edge to QE[23:0] data output	STAG = low, PIXS = high		0.25		t <sub>pix</sub>

(8) Link active or inactive is determined by amount of time detected between DE transitions. SCDT indicates link activity.





#### 2.3.2 Parameter Measurement Information

#### PARAMETER MEASUREMENT INFORMATION

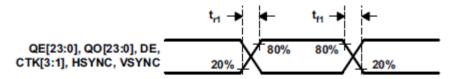


Figure 1. Rise and Fall Times of Data and Control Signals

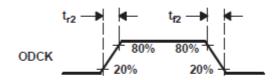


Figure 2. Rise and Fall Times of ODCK

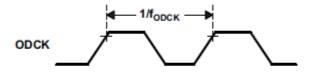


Figure 3. ODCK Frequency

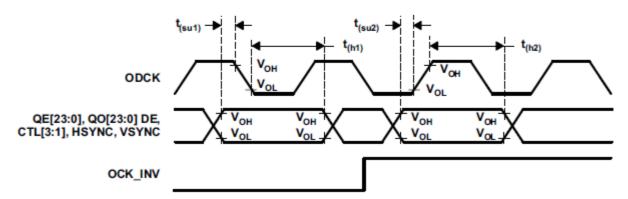


Figure 4. Data Setup and Hold Times to Rising and Falling Edges of ODCK



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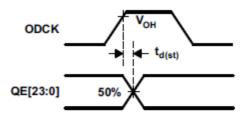


Figure 5. ODCK High to QE[23:0] Staggered Data Output

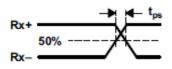


Figure 6. Analog Input Intra-Pair Differential Skew

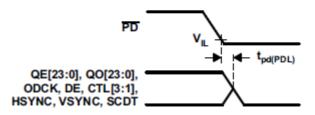


Figure 7. Delay From PD Low to Hi-Z Outputs

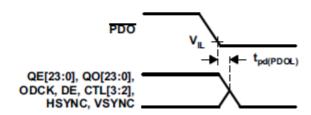


Figure 8. Delay From PDO Low to Hi-Z Outputs

#### PARAMETER MEASUREMENT INFORMATION (continued)

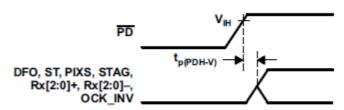


Figure 9. Delay From PD Low to High Before Inputs Are Active

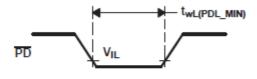
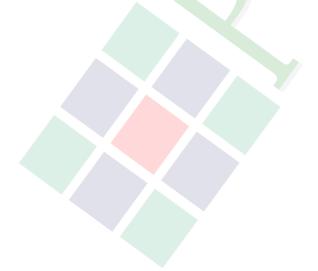


Figure 10. Minimum Time PD Low





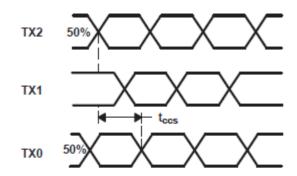


Figure 11. Analog Input Channel-to-Channel Skew

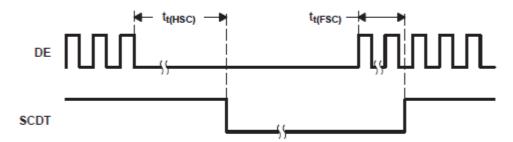


Figure 12. Time Between DE Transitions to SCDT Low and SCDT High

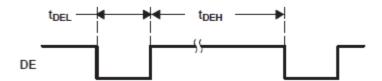


Figure 13. Minimum DE Low and Maximum DE High

#### **DETAILED DESCRIPTION**

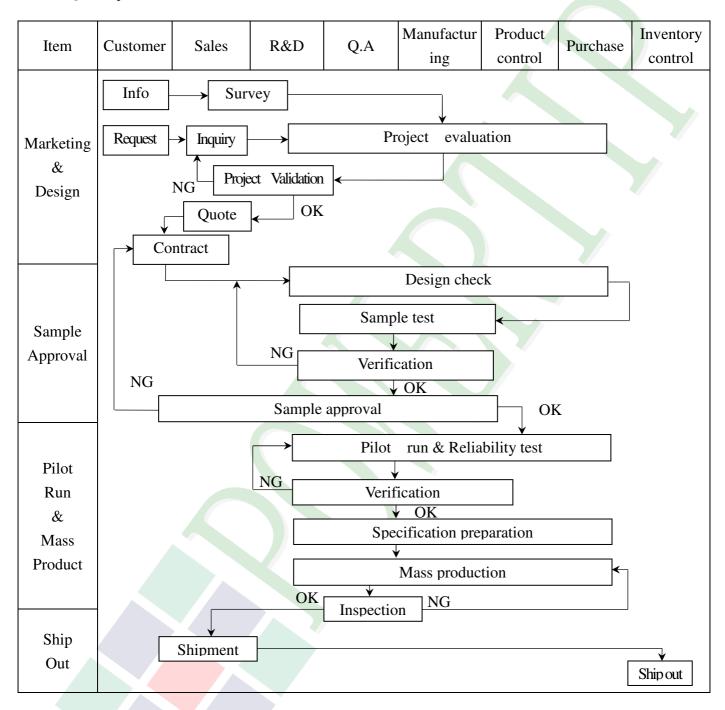


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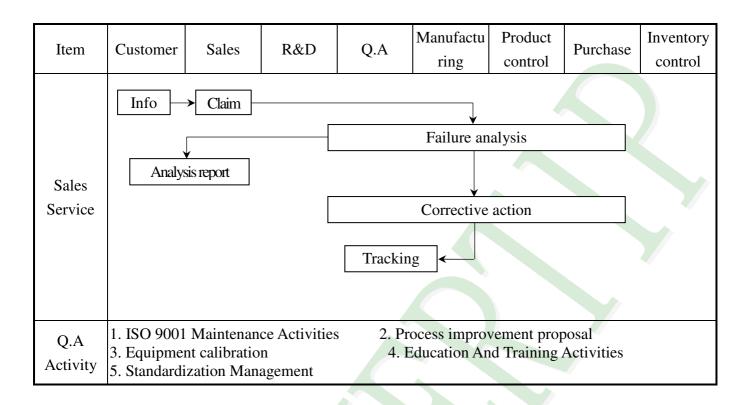


# 3. QUALITY ASSURANCE SYSTEM

### 3.1 Quality Assurance Flow Chart









### 3.2. Inspection Specification

**♦**Scope: The document shall be applied to TFT-LCD Module for 3.5" ~15" (Ver.B01).

♦ Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.

**◆**Equipment : Gauge · MIL-STD · Powertip Tester · Sample

◆Defect Level: Major Defect AQL: 0.4; Minor Defect AQL: 1.5

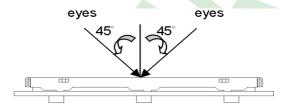
**OUT Going Defect Level: Sampling.** 

**♦**Standard of the product appearance test:

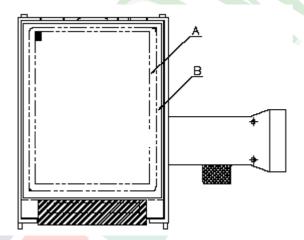
a. Manner of appearance test:

(1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.

(2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area: viewing area

**B** area: Outside of viewing area

(4). Standard of inspection: (Unit: mm)

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# ◆Specification For TFT-LCD Module 3. 5″ ~15″:

NO	Item	Criterion	Level			
		1. 1The part number is inconsistent with work order of production.	Major			
01	Product condition	1. 2 Mixed product types.				
		. 3 Assembled in inverse direction.				
02	Quantity	2. 1The quantity is inconsistent with work order of production.	Major			
03	Outline dimension	3.1 Product dimension and structure must conform to structure diagram.	Major			
		4. 1 Missing line character and icon.	Major			
		4. 2 No function or no display.	Major			
		4. 3 Display malfunction.	Major			
04	04 Electrical Testing	4. 4 LCD viewing angle defect.				
		4. 5 Current consumption exceeds product specifications.				
			4. 6 Mura can not be seen through 5% ND filter. (Mura: Under the normal examination angle of view,the picture has the non-uniform phenomenon.)	Minor		
		Item Acceptance (Q'ty)				
		Bright Dot ≤ 4				
	Dot defect	Dot Dark Dot ≤ 5				
	<b></b>	Defect Joint Dot ≤ 3				
05	(Bright dot > Dark dot)	Total ≤ 7	Minor			
	On -display	<ul> <li>5. 1 Inspection pattern: full white, full black, Red, Green and blue screens.</li> <li>5. 2 It is defined as dot defect if defect area &gt;1/2 dot.</li> <li>5. 3 The distance between two dot defect ≥5 mm.</li> <li>5. 4 Bright dot that can not be seen through 5% ND filter.</li> </ul>				



# **♦**Specification For TFT-LCD Module 3. 5″ ~15″:

<b>▼</b> Bpc			LCD Woddle 9. 9 419 ·						(ver.bur)
NO	Item		Criterion			Level			
		6. 1 Ro		Non-displa			nce (Q ty) B area		
	Black or white dot \ scratch \ contamination		0.25	$\Phi \le 0.$ $< \Phi \le 0.$ $\Phi > 0$ Total	50	5 0 5	Ignore		
	Round type $\begin{array}{c c}  & X & & \\  & & Y \\ \hline  & & Y \end{array}$			on-display o			Acceptanc	e (O'ty)	
06		mo	dule size	(L)	W	$\frac{\text{idth (W)}}{\text{W} \le 0.03}$	A area Igno e	B area	Minor
	$\Phi = (x+y)/2$ Line type	3.5"	to less 9"	L ≦10.0 L ≦5.0			4 2 As round	Ignore	
	V N N N N N N N N N N N N N N N N N N N				Total	W ≤ 0.05	type 5 Ignore		
	L L	9"	' to 15"	L ≦10.0			5 As round type	Ignore	
					Total	I	5		
		I	Dimension	(diameter :	Φ)	Accepta A area	nce (Q'ty) B are	ea	
		X		$\Phi \leq 0.25$		Ignore			
07	Polarizer Bubble			$\Phi \le 0.50$ $\Phi \le 0.80$		1	I av -		Minor
		X	0.50 <	$\Phi \ge 0.80$ $\Phi > 0.80$		0	Igno	re	
			7	Total		5			



# ◆Specification For TFT-LCD Module 3. 5″ ~15″:

NO	Item	Criterion		Level
		Z: The thickness of crack	Y : The width of crack. W : terminal length a : LCD side length	
		8. 1 General glass chip: 8. 1. 1 Chip on panel surface and cra	ack between panels:	
		Z	Z X	
08	The crack of glass	SP Y (OK)	[NG]	Minor
		Seal width Z	Y	
		X	z	
		≤ a Crack can't enter viewing area	≤1/2 t	
	X	≤ a Crack can't exceed the half of SP width.	1/2 t < Z ≤2 t	



# **♦**Specification For TFT-LCD Module 3. 5″ ~15″:

NO	Item	Criterion	Level
		Symbols:  X: The length of crack Z: The thickness of crack t: The thickness of glass  X: The width of crack W: terminal length a: LCD side length	ek.
		8. 1. 2 Corner crack:	
		X Y Z	
		$\leq$ 1/5 a Crack can't exceed the half of SP width. 1/2 t < Z $\leq$ 2	t
08	The aveals of along		Minor
VO	The crack of glass	8.2 Protrusion over terminal:	Millor
		8. 2. 1 Chip on electrode pad:	<u>↓</u> Z
		W X	
		X Y Z	
		Front $\leq a$ $\leq 1/2  \mathrm{W}$ $\leq t$	
		Back $\leq$ a $\leq$ W $\leq$ 1/2	t



# ◆Specification For TFT-LCD Module 3. 5″~15″:

X: The length of crack Z: The thickness of crack t: The thickness of glass a: LCD side length 8. 2. 2 Non-conductive portion:	NO	Item	Criterion	Level
glass  ① If the chipped area touches the ITO terminal, over 2/3 of  ● the ITO must remain and be inspected according to electrode terminal specifications.  8. 2. 3 Glass remain:  W  Pitch  X Y Z ≤ a ≤ 1/3 W ≤ t  8.2.4 Cracking		The crack of	Symbols:  X: The length of crack Z: The thickness of crack t: The thickness of glass  8. 2. 2 Non-conductive portion:  X Y Z  X Y Z  ≤ 1/3 a ≤ W ≤ t  O If the chipped area touches the ITO terminal, over 2/3 of electrode terminal specifications.  8. 2. 3 Glass remain:  X Y Z  ≤ a ≤ 1/3 W ≤ t	Level



# **♦**Specification For TFT-LCD Module 3. 5″ ~15″:

NO	Item	Criterion	Level
		9. 1 Backlight can't work normally.	Major
09	Backlight elements	9. 2 Backlight doesn't light or color is wrong.	Major
		9. 3 Illumination source flickers when lit.	Major
		10. 1 Pin type \quantity \dimension must match type in structure diagram.	Major
		10. 2 No short circuits in components on PCB or FPC.	Major
	General	10. 3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
10	appearance	10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10. 5 The folding and peeled off in polarizer are not acceptable.	Minor
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC ) is $\leq 1.5$ mm.	Minor



### 4. RELIABILITY TEST

### 4.1 Reliability Test Condition

(Ver.B01)

	Trendbility rest condition (ven.bor)				
NO.	TEST ITEM	TEST CO	ONDITION		
1	High Temperature Storage Test	Keep in +80 ±2°C 240 hrs			
2	Low Temperature Storage Test	Keep in −30 ±2°C 240 hrs			
3	High Temperature / High Humidity Storage Test	Keep in +60 ℃ /90% R.H duration for 240 hrs (Excluding the polarizer)			
			$\rightarrow$ +80°C $\rightarrow$ +25°C		
4	Temperature Cycling	(30mins) (5mins)	(30mins) (5mins)		
	Storage Test	20 Cycle			
		Air Discharge:	Contact Discharge:		
		Apply 2 KV with 5 times	Apply 250 V with 5 times		
		Discharge for each polarity +/-	discharge for each polarity +/-		
		1. Temperature ambiance : $15$ $^{\circ}$ $\sim$	35℃		
5	ESD Test	2.Humidity relative: 30%~60%			
<b>"</b>	ESD Test	3.Energy Storage Capacitance(Cs-	_		
		4.Discharge Resistance(Rd): 330 C	2±10%		
		5.Discharge, mode of operation :			
			uccessive discharges at least 1 sec)		
		(Tolerance if the output voltage in	·		
	Vibration Test	1.Sine wave 10∼55 Hz frequency	(1 min/sweep)		
6	(Packaged)	2. The amplitude of vibration :1.5			
	, 0	3.Each direction (X · Y · Z) durat	ion for 2 Hrs		
		Packing Weight (Kg)	Drop Height (cm)		
		0 ~ 45.4	122		
_	<b>Drop Test</b>	45.4 ~ 90.8	76		
7	(Packaged)	90.8 ~ 454	61		
		Over 454	46		
		Drop Direction : 1 corner / 3 edg	es / 6 sides each 1time		

#### **©Result Evaluation Criteria:**

Under the display quality test conditions with normal operations with normal operation state. Do not change these conditions as such changes may affect practical display function.

(Normal operation state)

Temperature: +20~30 °C Humidity: 50~70%

Atmospheric pressure: 86~106Kpa



# 5. PRECAUTION RELATING PRODUCT HANDLING

#### **5.1 SAFETY**

- 5.1.1 If the LCD panel breaks , be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

#### **5.2 HANDLING**

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is 320±10°C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.

### **5.3 STORAGE**

- 5.3.1 Store the panel or module in a dark place where the temperature is  $25^{\circ}$ C  $\pm 5^{\circ}$ C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

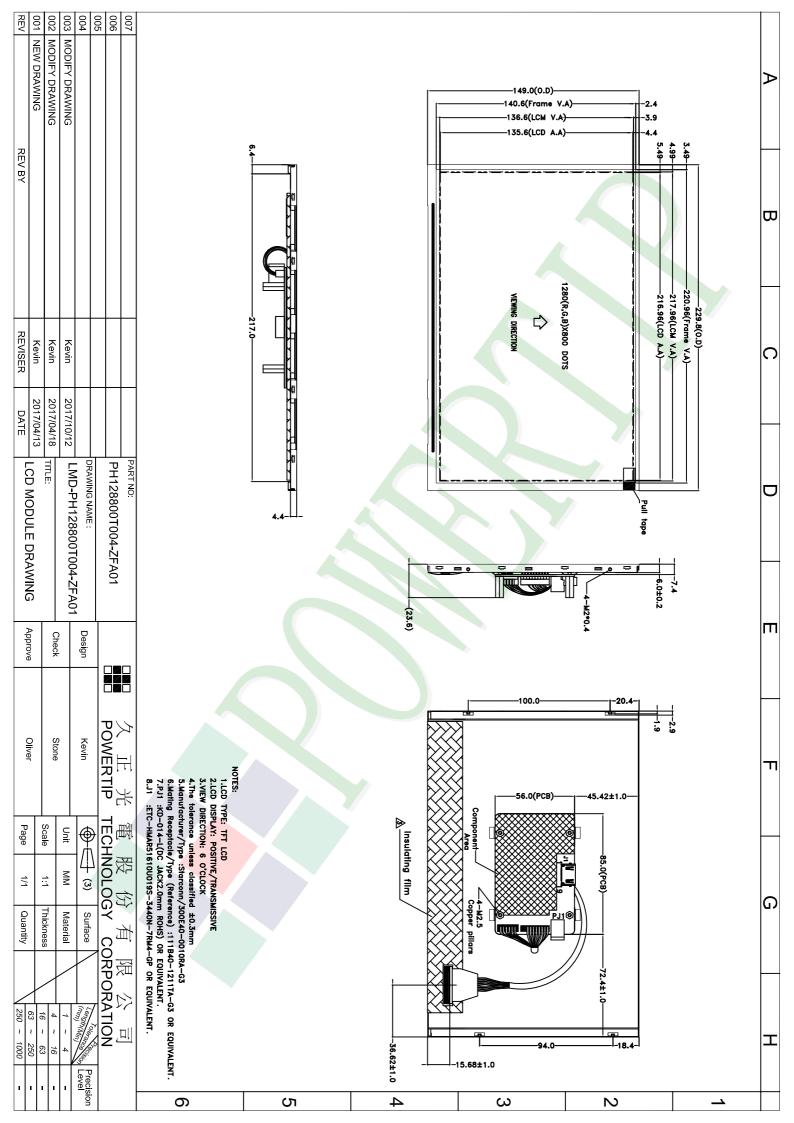
#### **5.4 TERMS OF WARRANTY**

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



Check Approve Contact LCM包裝規格書 Ver.003 LCM Packaging Specifications Documents NO. PKG-PH128800T004-ZFA01 Kevin Oliver Stone (For Tray) 1.包裝材料規格表 (Packaging Material): (per carton) 1Pcs Weight No. Item Model Dimensions (mm) Ouantity Total Weight 229.8 X 149 1 成品 (LCD) PH128800T004-ZFA01 8 0.2567 2.0536 2 多層薄膜(1)POF OTFILM0BA03ABA 4 3 TRAY 盤 (2)Tray TY00000000425 352 X 260 X 35.8 12 0.15 1.8 4 內盒(3)Product Box BX38327211AABA 383 X 270 X 110 0.25 4 1.0 2 OTPLB00PL08ABA 保利龍板(4)Polylon board 550 X 393 X 20 0.0284 0.0568 6 外紙箱(5)Carton 570 X 410 X 265 1 BX57041027CCBA 1.4208 1.4208 7 舒美墊(6)EPE 0.0032 OTFOAMEP0001BA 333X 218 X 2.0 4 0.0128 8 舒美墊(7)EPE 0.044 FOAM000000047 350 X 255 X 5 0.011 4 9 2.一 整箱總重量 (Total LCD Weight in carton): Kg±10% 3.單箱數量規格表 (Packaging Specifications and Quantity): (1)LCD quantity per box : no per tray x no of tray 1 2 x no of boxes (2) Total LCD quantity in carton: quantity per box 2 8 4 = Use empty tray (4)保利龍板 空盤 Polylon board (1)多層薄膜 **POF** Put products into the tray (2)TRAY 盤 (4)保利龍板 Tray Polylon board (5)外紙箱 (7)舒美墊 Carton **EPE** (6)舒美墊 Tray stacking (3)内盒 Product Box 特 記 事 項 (REMARK) 斜角 Detail B 5. LCM上面放置2.0t EPE(舒美墊) 333 Tray 2 圓角 Tray 1 4. TRAY盤相疊時,需旋轉180度,請詳見B視圖 Rotate tray 180 degrees and place on top of stack. 裁切線 Check the tray stack using Fig. B. POWERTIP TECH. CORP.